

PRINTED CIRCUIT BOARD, MAGNETIC DISK DEVICE, AND METHOD FOR
MANUFACTURING THE PRINTED CIRCUIT BOARD

ABSTRACT

5 An insulating substrate includes a first area where a semiconductor device is disposed, a second area where a wiring electrically connecting to the semiconductor device is disposed, and a third area where a terminal electrically connecting to the wiring is disposed. A first wiring is
10 disposed on a main surface of the insulating substrate in the second area and connects to the second wiring disposed in the first area and the terminal disposed in the third area through first and second interlayer connecting portions. With this configuration, the second wiring need not be disposed in the
15 second area, so that flexibility in the second area used as a connecting portion increases.

FIG. 1A